

Application No.: 10/790,723Docket No.: 2336-247

## ABSTRACT

~~Disclosed herein is a wafer level package for a micro device, such as an FBAR device. The~~  
A wafer level package ~~includes~~ comprises a device wafer having a micro device, and bonding pads  
which are connected to the micro device, and ~~which are~~ formed at one surface of the device wafer,  
via connectors extending from the bonding pads to the other surface of the device wafer, external  
bonding pads formed at the other surface of the device wafer and ~~adapted to be~~ connected to the  
bonding pads through the via connectors, ~~respectively~~, and a cap structure bonded to one surface of  
the device wafer so as to allow the micro device to be insulated and hermetically sealed.